

What is claimed is:**I CLAIM:**

1. A method of assembling a packaged electronic module for use with a smart card, the method comprising the steps:

(A) providing a first contact plate including a first electrical connector, the first electrical connector configured with a first surface of the first contact plate;

(B) providing a first printed circuit including a second electrical connector, the second electrical connector configured with a first surface of the first printed circuit;

(C) electrically mating the first electrical connector with the second electrical connector to form a packaged electronic module.

2. The method of claim 1 wherein the first surface of the first contact plate includes the bottom of the first contact plate and the first surface of the first printed circuit includes the top of the first printed circuit.

3. The method of claim 1 wherein the first contact plate includes one or more contact points and the first electrical connector of the first contact plate is electrically connected to at least one of the one or more contact points.

4. The method of claim 1 wherein the first printed circuit includes one or more electronic components and the first electrical connector of the first printed circuit is electrically connected to at least one of the one or more electronic components.

5. The method of claim 4 wherein the electrical mating of the first electrical connector with the second electrical connector in (C) forms a gap between the first surface of the first contact plate and the first surface of the first printed circuit, and wherein at least one of the one or more electronic components fits within the gap.

6. The method of claim 1 wherein the first printed circuit includes one or more value add components selected from the group: a display, a fingerprint sensor and an LED device.

7. The method of claim 1 wherein the first contact plate and/or the first printed circuit is configured with an antenna.

8. The method of claim 1 wherein the first contact plate is included in a first contact plate tape.

9. The method of claim 1 wherein the first printed circuit is included in a first printed circuit tape.

10. A method of assembling a packaged electronic module for use with a smart card, the method comprising the steps:

(A) providing a first contact plate including a first electrical connector, the first electrical connector configured with a first surface of the first contact plate;

(B) providing a first printed circuit including a second electrical connector configured with a first surface of the first printed circuit, and a third electrical connector configured with a second surface of the printed circuit;

(C) providing a second printed circuit including a first contact area configured with a first surface of the second printed circuit;

(D) electrically mating the first electrical connector with the second electrical connector and the third electrical connector with the first contact area to form a packaged electronic module.

11. The method of claim 10 wherein the first surface of the first contact plate includes the bottom of the first contact plate, the first surface of the first printed circuit includes the top of the first printed circuit, the second surface of the first printed circuit includes the bottom of the first printed circuit, and the first surface of the second printed circuit includes the top of the second printed circuit.

12. The method of claim 10 wherein the second electrical connector is electrically connected to the third electrical connector.

13. The method of claim 10 wherein the first printed circuit includes one or more first electronic components and the first electrical connector of the first printed circuit is electrically connected to at least one of the one or more first electronic components.

14. The method of claim 10 wherein the first contact plate and/or the first printed circuit and/or the second printed circuit is configured with an antenna.

15. The method of claim 13 wherein the electrical mating of the first electrical connector with the second electrical connector in (D) forms a first gap between the first surface of the first contact plate and the first surface of the first printed circuit, and wherein at least one of the one or more first electronic components fits within the first gap.

16. The method of claim 10 wherein the second printed circuit includes one or more second electronic components and the first contact area of the second printed circuit is electrically connected to at least one of the one or more second electronic components.

17. The method of claim 16 wherein the electrical mating of the third electrical connector with the first contact area in (D) forms a second gap between the second surface of the first printed circuit and the first surface of the second printed circuit, and wherein at least one of the one or more second electronic components fits within the second gap.

18. The method of claim 10 wherein the second printed circuit includes one or more value add components selected from the group: a display, a fingerprint sensor and an LED device.

19. The method of claim 10 wherein the first contact area includes a fourth electrical connector.